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Oshusa
4-10-02JC997 U.S. PTO
10/075465
02/15/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Hisato OYAMATSU

SERIAL NO: NEW APPLICATION

GAU:

FILED: Herewith

EXAMINER:

FOR: SEMICONDUCTOR DEVICE HAVING PATTERNED SOI STRUCTURE AND METHOD FOR FABRICATING THE SAME

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

- The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- A check is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.
- A check is attached in the amount required under 37 CFR §1.17(p).

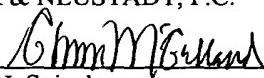
CERTIFICATION

- Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- Please charge any additional fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

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Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 219660US2S		SERIAL NO. NEW APPLICATION	
LIST OF REFERENCES CITED BY APPLICANT		APPLICANT		Hisato OYAMATSU			
		FILING DATE Herewith		GROUP			
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
AA							
AB							
AC							
AD							
AE							
AF							
AG							
AH							
AI							
AJ							
AK							
AL							
AM							
AN							
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION		
					YES	NO	
AO							
AP							
AQ							
AR							
AS							
AT							
AU							
AV							
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)							
AW	Robert HANNON, et al., "0.25 ^m m Merged Bulk DRAM and SOI Logic Using Patterned SOI", SYMPOSIUM ON VLSI TECHNOLOGY DIGEST OF TECHNICAL PAPERS, 2000 (2 pages)						
AX							
AY							
AZ					<input type="checkbox"/> Additional References sheet(s) attached		
Examiner					Date Considered		
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

1997 U.S. PTI
10/075165
02/15/02

DOCKET NO.: 219660US2S

page 1 of 1

jc97 U.S. PRO
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STATEMENT OF RELEVANCY

Reference AW on Form PTO-1449:

This paper shows $0.25\mu\text{m}$ Merged bulk DRAM and SOI Logic using patterned SOI.